

April 2008

# FDS5351

# N-Channel PowerTrench<sup>®</sup> MOSFET 60V, 6.1A, $35m\Omega$

# **Features**

- Max  $r_{DS(on)} = 35m\Omega$  at  $V_{GS} = 10V$ ,  $I_D = 6.1A$
- Max  $r_{DS(on)} = 42m\Omega$  at  $V_{GS} = 4.5V$ ,  $I_D = 5.5A$
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- 100% UIL Tested
- RoHS Compliant

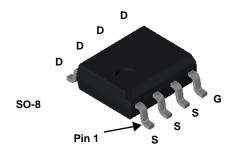


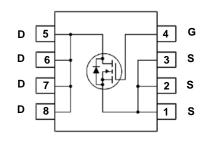
# **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

# **Application**

- Inverter Switch
- Synchronous Rectifier
- Load Switch





# **MOSFET Maximum Ratings** $T_A = 25$ °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage		60	V
$V_{GS}$	Gate to Source Voltage		±20	V
	Drain Current -Continuous		6.1	^
'D	-Pulsed		30	A
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	73	mJ
D	Power Dissipation T <sub>A</sub> = 25°C	(Note 1a)	5	W
$P_{D}$	Power Dissipation $T_A = 25^{\circ}C$	(Note 1b)	2.5	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C	

### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS5351	FDS5351	SO-8	13"	12mm	2500units

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted Parameter

Off Characteristics						
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		55		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 48V, V_{GS} = 0V$			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

**Test Conditions** 

Min

Тур

Max

Units

### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.0	2.0	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to 25°C		-6.2		mV/°C
		$V_{GS} = 10V, I_D = 6.1A$		26.5	35.0	
r <sub>DS(on)</sub>	r <sub>DS(on)</sub> Static Drain to Source On Resistance	$V_{GS} = 4.5V, I_D = 5.5A$		32.4	42.0	mΩ
	$V_{GS} = 10V$ , $I_D = 6.1A$ , $T_J = 125$ °C		44.5	58.8		
g <sub>FS</sub>	Forward Transconductance	$V_{DD} = 5V, I_D = 6.1A$		24		S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 20V V 0V		985	1310	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz		90	120	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			50	75	pF
$R_g$	Gate Resistance	f = 1MHz		1.7		Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	.,	8	16	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 30V, I_{D} = 6.1A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	3	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 652	21	34	ns
t <sub>f</sub>	Fall Time		2	10	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0V to 10V	19	27	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 4.5V$ $V_{DD} = 30V,$ $I_{D} = 6.1A$	9	13	nC
Q <sub>gs</sub>	Gate to Source Charge	1 <sub>D</sub> = 6.1A	3		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		3.5		nC

# **Drain-Source Diode Characteristics**

	$V_{GS} = 0V, I_S = 6.1A$	(Note 2)	0.82	1.3	\/	
V <sub>SD</sub>	Source to Drain Diode Forward voltage	$V_{GS} = 0V, I_S = 2.1A$	(Note 2)	0.76	1.2	V
t <sub>rr</sub>	Reverse Recovery Time			24	38	ns
Q <sub>rr</sub>	Reverse Recovery Charge			15	27	nC

<sup>1.</sup> R<sub>0,1A</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0,1C</sub> is guaranteed by design while R<sub>0,CA</sub> is determined by the user's board design.



a) 50°C/W when mounted on a 1in<sup>2</sup> pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width <  $300\mu s$ , Duty cycle < 2.0%.
- 3. UIL condition: Starting  $T_J$  = 25°C, L = 3mH,  $I_{AS}$  = 7A,  $V_{DD}$  = 60V,  $V_{GS}$  = 10V.

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

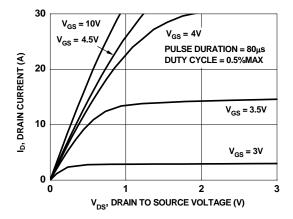


Figure 1. On-Region Characteristics

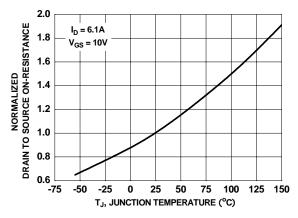


Figure 3. Normalized On-Resistance vs Junction Temperature

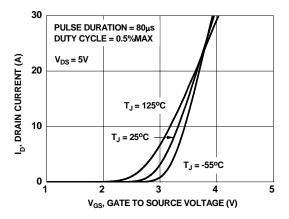


Figure 5. Transfer Characteristics

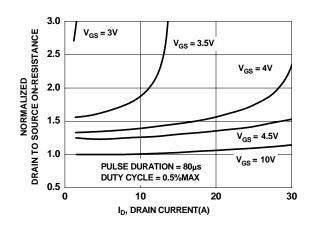


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

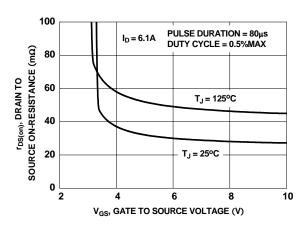


Figure 4. On-Resistance vs Gate to Source Voltage

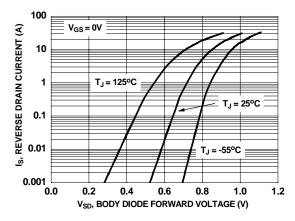


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

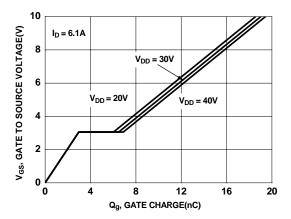


Figure 7. Gate Charge Characteristics

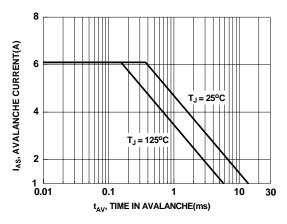


Figure 9. Unclamped Inductive Switching Capability

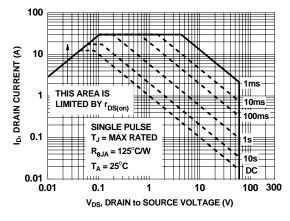


Figure 11. Forward Bias Safe Operating Area

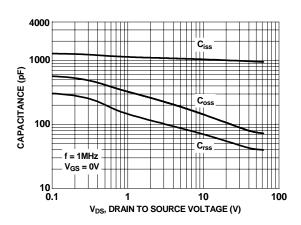


Figure 8. Capacitance vs Drain to Source Voltage

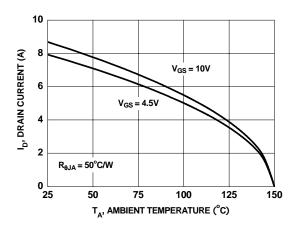


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

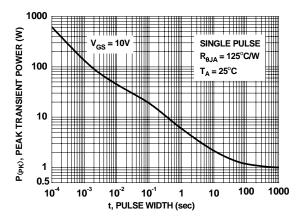


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

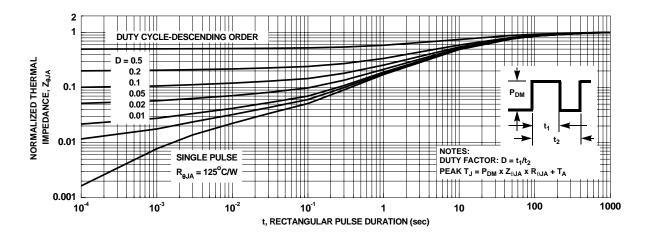


Figure 13. Transient Thermal Response Curve





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